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## PAD REMOVAL PROCEDURES

REMOVAL FROM MACHINE PLATEN BEGINS ONCE ALL POLISHING IS COMPLETED.

### **REQUIRED EQUIPMENT/MATERIALS**

- Isopropyl alcohol and dispense bottle
- No-lint lab wipes
- Thin plastic putty knife

### **PREPARATION**

Prior to opening the tool for pad removal, ensure that the surface of the pad is clean and all slurry residue is removed. This can be accomplished by rotating the platen while using a high-pressure rinse.

*Note: It's easier to remove the pad from a platen that is at a higher temperature. If the process allows, increase platen temperature or discontinue platen cooling. Ideal tape application and removal temperature range: 70°F to 100°F, (21°C to 38°C).*

### **SAFETY/PRECAUTIONS**

- Observe commonly accepted industrial safety procedures regarding eye, hand, head, back, and foot protection.
- Follow lockout / tagout procedures as necessary.
- Be careful not to overextend back when removing pads from platens. Use step stool if necessary.
- Use PPE (Personal Protective Equipment) when handling cutting instruments.

### **PROCEDURE** - INCLUDES 9 STEPS

- 1) Rotate the platen to remove excess water.
- 2) If needed, rotate the tool cover to gain access to polishing head and platen. To gain proper access to the platen and pad follow standard procedure, removing the polishing head above the pad to be removed. Use your fingers or thin plastic putty knife to separate pad edge from platen, beginning around pad edge on the side of the platen and opposite from where pad will be pulled. Do this to approximately 45° of the pad circumference.

*Note: This step creates a "handle" used to pull the pad off. The "handle" should be across the platen from where you stand to pull the pad. It's normally easier to remove top and bottom pad together. This is usually the case removing pads that are machine stacked. Occasionally, when removing pads stacked individually on the platen, the top pad will separate from the bottom pad. In this case, remove both pads individually per this procedure.*

- 3) Now remove pad from platen by reaching across the platen and pulling pad by the handle towards you. Do this slowly so as not to exert excessive force.

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## PAD REMOVAL PROCEDURES *CONTINUED*

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### **PROCEDURE** - *INCLUDES 9 STEPS*

- 4) Using both hands, grab the pad at any open end of the platen, stand straight, positioning body so as to not overextend the back. If you cannot lift the pad, use a utility knife to pry up a section.
- 5) Carefully pull pad towards body. If pad is hard to pull off, work it off slowly.  
*Note: Pad removal may be easier if a small amount of isopropyl alcohol is applied under the pad at the leading edge pad/platen interface. This should soften the adhesive. Can be done periodically during pad pulling.*
- 6) Continue to pull the pad towards you, folding pad on top of itself under the tool cross.  
*Note: A second person assisting with initial pad removal increases the ability to get this removal process started. Pad removal should become easier once approximately 50% has been removed.*
- 7) Pad removal may be easier by alternately pulling slightly left and slightly right of center position directly across from you. Make sure to reposition yourself prior to beginning the pull from the alternate positions.
- 8) As pad removal continues and the pad folds over itself, be careful that the pad's underside (adhesive side) does not come in contact with and stick to the polishing head mounting plate or other areas of equipment.
- 9) Once pad has been completely removed, cover adhesive side with a release liner sheet. If discarding the pad, fold in half with the adhesive sides in contact with each other.



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